

II. Listing of Claims

1-20. (Cancelled).

21. (Original) An electronic circuit assembly for connecting an electronic component thereto, comprising:

an electrically insulative substrate;

at least two mounting pads disposed on said substrate in matched relation with respective terminations of the electronic component; and

at least one metallic bump attached to each mounting pad within a projected footprint of the electronic component.

22. (Original) An electronic circuit assembly according to claim 21, wherein said at least one bump on each mounting pad is/are arranged generally symmetrically thereon with respect to a central longitudinal axis of said projected footprint.

23. (Original) An electronic circuit assembly according to claim 21, wherein said mounting pads are made of a first metal and said metallic bumps are made of a second metal.

24. (Original) An electronic circuit assembly according to claim 23, wherein said first metal is copper and said second metal is aluminum.

25. (Original) An electronic circuit assembly, comprising:
an electrically insulative substrate;
at least two mounting pads disposed on said substrate;

at least one metallic bump attached to a top surface of each mounting pad;

an electronic component having at least two terminations thereon, said component being disposed such that each termination rests atop a respective one of said mounting pads in contact with said at least one metallic bump atop each pad; and

a joint of electrically conductive bonding material connecting each termination with a respective one of said mounting pads.

26. (Original) An electronic circuit assembly according to claim 25, wherein said mounting pads are made of copper and said bumps are made of aluminum.

27. (Original) An electronic circuit assembly according to claim 25, wherein said bonding material is solder or electrically conductive adhesive.

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concluded